



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ035N03LS G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000896720						
<b>Package</b>		PG-TSDSON-8-22		<b>Weight*</b>		36.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.836	4.98	4.98	49814	49814
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		64	
	non noble metal	zinc	7440-66-6	0.009	0.03		257	
	non noble metal	iron	7439-89-6	0.189	0.51		5137	
wire	non noble metal	copper	7440-50-8	7.689	20.86	21.41	208577	214035
	noble metal	gold	7440-57-5	0.078	0.21	0.21	2108	2108
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		956	
	plastics	epoxy resin	-	1.815	4.92		49238	
	inorganic material	silicondioxide	60676-86-0	15.772	42.81	47.83	427846	478040
leadfinish	non noble metal	tin	7440-31-5	0.370	1.00	1.00	10039	10039
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2192	2192
solder	non noble metal	tin	7440-31-5	0.090	0.24		2449	
	non noble metal	lead	7439-92-1	1.715	4.65	4.89	46529	48978
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		106	
	non noble metal	iron	7439-89-6	0.078	0.21		2126	
	non noble metal	copper	7440-50-8	3.182	8.63	8.85	86312	88571
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		127	
	non noble metal	iron	7439-89-6	0.094	0.25		2549	
	non noble metal	copper	7440-50-8	3.816	10.35	10.61	103515	106223
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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